

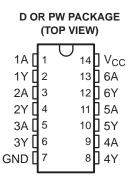
FEATURES

• Controlled Baseline

 One Assembly/Test Site, One Fabrication Site

- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Operates From 2 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II



DESCRIPTION/ORDERING INFORMATION

The SN74LVC14A hex Schmitt-trigger inverter is designed for 2.7-V to 3.6-V V_{CC} operation.

The device contains six independent inverters and performs the Boolean function $Y = \overline{A}$.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

T _A	PACKA	GE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Reel of 2500	SN74LVC14AQDREP	LVC14AE
-40°C 10 125°C	TSSOP – PW	Reel of 2000	SN74LVC14AQPWREP	LVC14AE
–55°C to 125°C	SOIC – D	Reel of 2500	SN74LVC14AMDREP	LVC14AE

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCT	ION	TABL	Е
(EACH	INV	ERTEF	Z)

INPUT A	OUTPUT Y
Н	L
L	Н

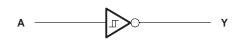


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SN74LVC14A-EP HEX SCHMITT-TRIGGER INVERTER SCAS732C-NOVEMBER 2003-REVISED JUNE 2006



LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V _{CC} or GN	ID		±100	mA
0	Deckers thermal impedance ⁽⁴⁾	D package		133.5	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾	PW package		113	-C/w
T _{stg}	Storage temperature range ⁽⁵⁾		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

(5) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT	
V	Supply voltage	Operating		3.6	V	
V _{CC}	Supply voltage	Data retention only	1.5		V	
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	V _{CC}	V	
	High lovel output ourrent	$V_{CC} = 2.7 V$		-12	mA	
IOH	High-level output current	$V_{CC} = 3 V$		-24	ШA	
		V _{CC} = 2.7 V		12	0	
I _{OL}	Low-level output current	$V_{CC} = 3 V$		24	mA	
T _A	Operating free-air temperature		-40	125	°C	

 All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, Implications of Slow or Floating CMOS Inputs (SCBA004).

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹) MAX	UNIT
V _{T+}		2.7 V	0.8	2	
Positive-going		3 V	0.9	2	V
threshold		3.6 V	1.1	2	
V _{T-}		2.7 V	0.4	1.4	
Negative-going		3 V	0.6	1.5	V
threshold		3.6 V	0.8	1.7	
ΔV_T		2.7 V	0.3	1.1	
Hysteresis		3 V	0.3	1.2	V
$(V_{T+} - V_{T-})$		3.6 V	0.3	1.2	
	I _{OH} = -100 μA	2.7 V to 3.6 V	V _{CC} – 0.2		
	40 40	2.7 V	2.2		V
V _{OH}	$I_{OH} = -12 \text{ mA}$	3 V	2.4		
	$I_{OH} = -24 \text{ mA}$	3 V	2.2		
	I _{OL} = 100 μA	2.7 V to 3.6 V		0.2	
V _{OL}	I _{OL} = 12 mA	2.7 V		0.4	V
	$I_{OL} = 24 \text{ mA}$	3 V		0.55	
I _I	$V_{I} = 5.5 \text{ V or GND}$	3.6 V		±5	μA
I _{CC}	$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	3.6 V		10	μA
ΔI_{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	2.7 V to 3.6 V		500	μA
Ci	$V_1 = V_{CC}$ or GND	3.3 V	:	5	pF

(1) All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =	2.7 V	V _{CC} = 1 ± 0.3	UNIT	
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	
t _{pd}	А	Y		7.5	1	6.4	ns

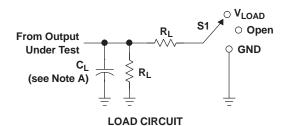
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST	$V_{CC} = 2.5 V$	V _{CC} = 3.3 V	UNIT
		CONDITIONS	TYP	TYP	UNIT
C_{pd}	Power dissipation capacitance per inverter	f = 10 MHz	12	15	pF

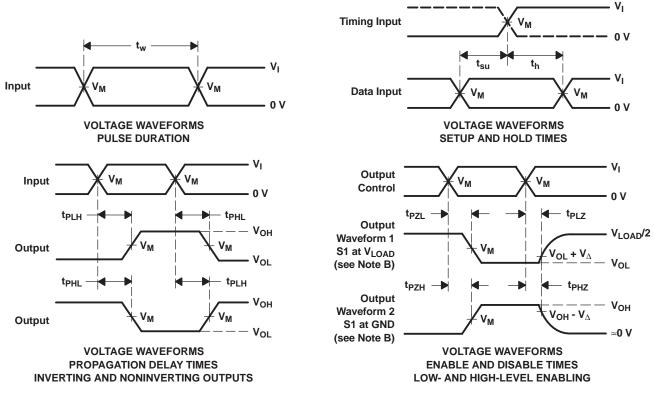


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	VLOAD
t _{PHZ} /t _{PZH}	GND

V	INPUTS				•		N
V _{CC}	VI t _r /t _f	t _r /t _f	VM	V _{LOAD}	CL	RL	V_{Δ}
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES: A. C_{L} includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
	. ,				-	.,	(6)	.,			
SN74LVC14AQDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC14AE	Samples
SN74LVC14AQPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC14AE	Samples
V62/04658-01XE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC14AE	Samples
V62/04658-01YE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC14AE	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

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OTHER QUALIFIED VERSIONS OF SN74LVC14A-EP :

- Catalog: SN74LVC14A
- Automotive: SN74LVC14A-Q1
- Military: SN54LVC14A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



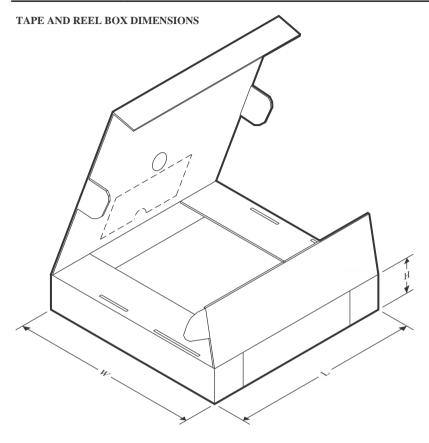
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC14AQDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC14AQPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

10-Jan-2024



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC14AQDREP	SOIC	D	14	2500	333.2	345.9	28.6
SN74LVC14AQPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



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